



Material Content Data Sheet



Sales Product Name		IPU50R3K0CE		Issued		25. September 2017		
MA#		MA001479382						
Package		PG-TO251-3-345		Weight*		384.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.853	0.22	0.22	2219	2219
leadframe	non noble metal	iron	7439-89-6	0.209	0.05		543	
	inorganic material	phosphorus	7723-14-0	0.063	0.02		163	
	non noble metal	copper	7440-50-8	208.238	54.18	54.25	541836	542542
wire	non noble metal	aluminium	7429-90-5	1.382	0.36	0.36	3595	3595
encapsulation	organic material	carbon black	1333-86-4	0.702	0.18		1826	
	plastics	epoxy resin	-	18.944	4.93		49291	
	inorganic material	silicondioxide	60676-86-0	120.678	31.40	36.51	314005	365122
leadfinish	non noble metal	tin	7440-31-5	7.055	1.84	1.84	18356	18356
solder	noble metal	silver	7440-22-4	0.032	0.01		84	
	non noble metal	tin	7440-31-5	0.026	0.01		67	
	non noble metal	lead	7439-92-1	1.229	0.32	0.34	3197	3348
heatspreader	non noble metal	iron	7439-89-6	0.025	0.01		65	
	inorganic material	phosphorus	7723-14-0	0.007	0.00		19	
	non noble metal	copper	7440-50-8	24.879	6.47	6.48	64734	64818
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com